

REPLACEMENT ABSTRACT:

Please replace the present abstract with the following rewritten abstract:

A process for transfer of at least one thin film of solid material delimited in an initial substrate. The process includes a step in which a layer of inclusions is formed in the initial substrate at a depth corresponding to the required thickness of the thin film. These inclusions are designed to form traps for gaseous compounds which subsequently are implanted. In a subsequent step gaseous compounds are implanted in a manner to convey the gaseous compounds into the layer of inclusions. The dose of implanted gaseous compounds is made sufficient to cause the formation of microcavities to form a fracture plane along which the thin film can be separated from the remainder of the substrate.

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